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General Descriptions

- DDC144NS features discrete dual NPN transistors that can support continuous maximum current up to 100 mA. It is suited for applications where the load needs to be turned on and off using circuits like micro-controllers, comparators, etc., particularly at a point of load. The component devices can be used as a part of a circuit or as a stand alone discrete device.

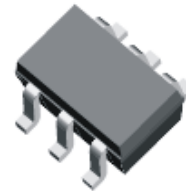


Fig. 1: SOT-363

Features

- Epitaxial Planar Die Construction
- Ideally Suited for Automated Assembly Processes
- Lead Free By Design/RoHS Compliant (Note 1)**
- "Green" Device (Note 2)**

Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: See Figure 2
- Terminals: Finish - Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.0065 grams (approximate)

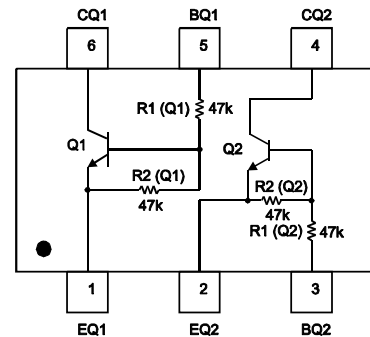


Fig. 2: Schematic and Pin Configuration

Maximum Ratings, Total Device

@T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3)	P _d	200	mW
Thermal Resistance, Junction to Ambient Air (Note 3)	R _{θJA}	625	°C/W
Operating and Storage Temperature Range	T _i , T _{STG}	-55 to +150	°C
Collector Current	I _{C(max)}	100	mA

Maximum Ratings:

Sub-Component Device - Pre-Biased NPN Transistor

@T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Supply Voltage	V _{CC}	50	V
Input Voltage	V _{in}	-10 to +40	V
Output Current	I _O	100	mA

Electrical Characteristics:

Pre-Biased NPN Transistor

@T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Input Voltage	V _{I(off)}	0.5	1.1	—	V	V _{CC} = 5V, I _O = 100uA
	V _{I(on)}	—	1.5	3	V	V _O = 0.3V, I _O = 2mA
Output Voltage	V _{O(on)}	—	0.1	0.3	V	I _O /I _I = 10mA/0.5mA
Input Current	I _I	—	—	0.18	mA	V _I = 5V
Output Current	I _{O(off)}	—	—	0.5	uA	V _{CC} = 50V, V _I = 0V
DC Current Gain	G _I	100	—	—	—	V _O = 5V, I _O = 5mA
Input Resistor (R1) Tolerance	Δ R1	-30	—	+30	%	—
Resistance Ratio Tolerance	R2/R1	-20	—	+20	%	—
Gain-Bandwidth Product	f _T	—	250	—	MHz	V _{CE} = 10V, I _E = 5mA, f = 100 MHz

- Notes:
- No purposefully added lead.
 - Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 - Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on page 4 or go to Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>

Typical Characteristics of NPN Transistor

@ $T_A = 25^\circ\text{C}$ unless otherwise specified

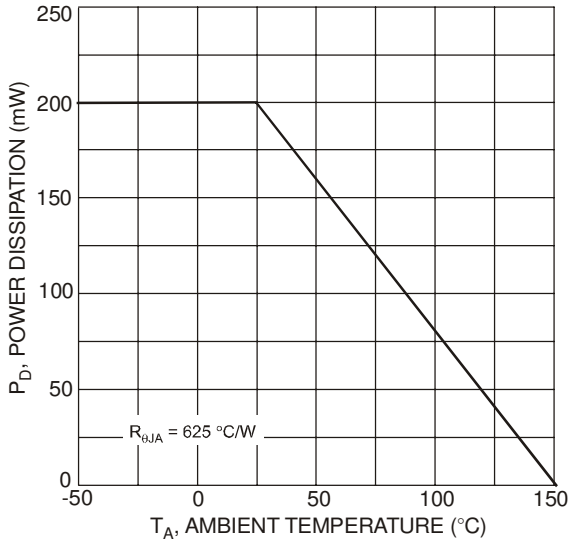


Fig. 3 Derating Curve

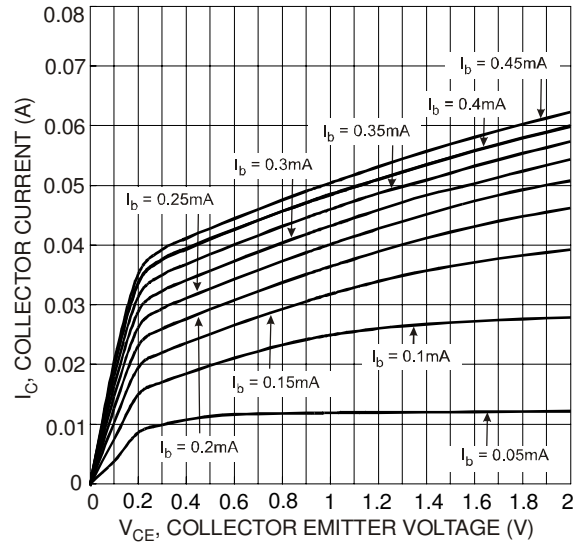


Fig. 4 Typical V_{CE} vs. I_C

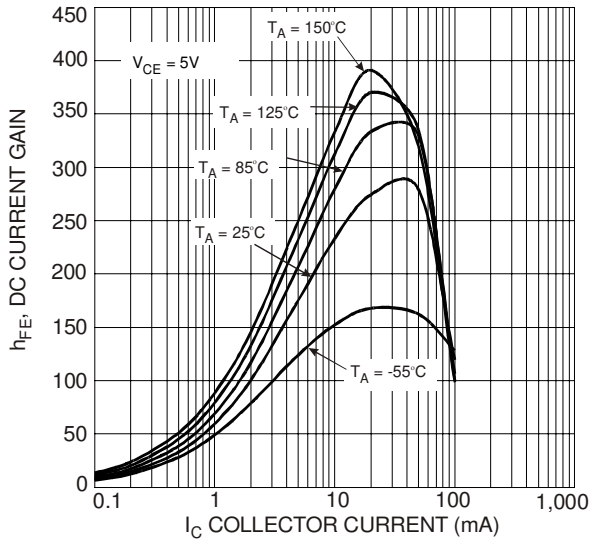


Fig. 5 Typical DC Current Gain

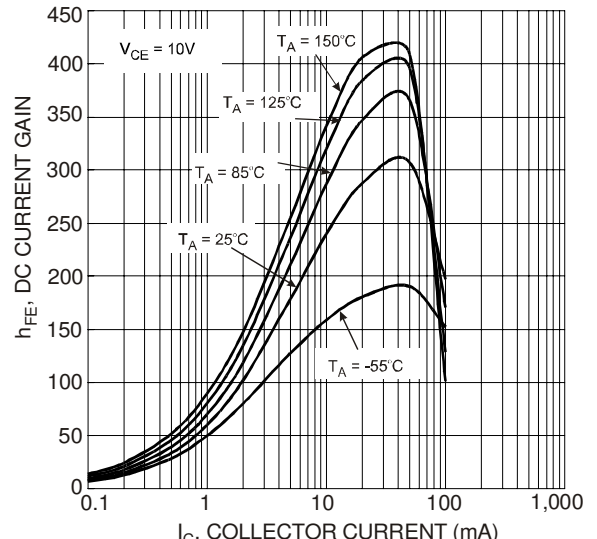


Fig. 6 Typical DC Current Gain

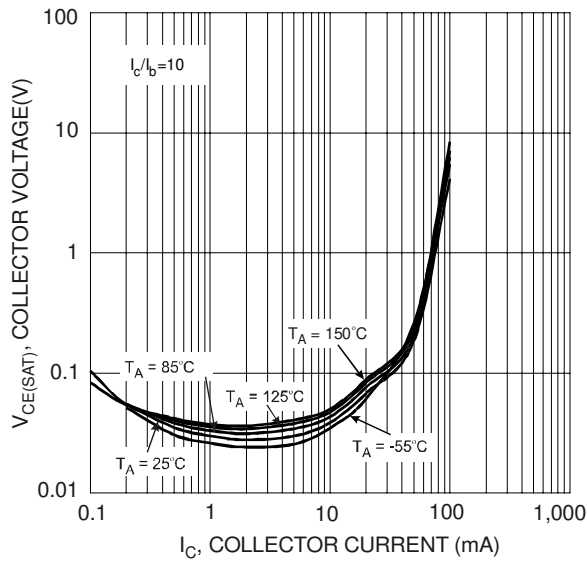


Fig. 7 Typical $V_{CE(SAT)}$ vs. I_C

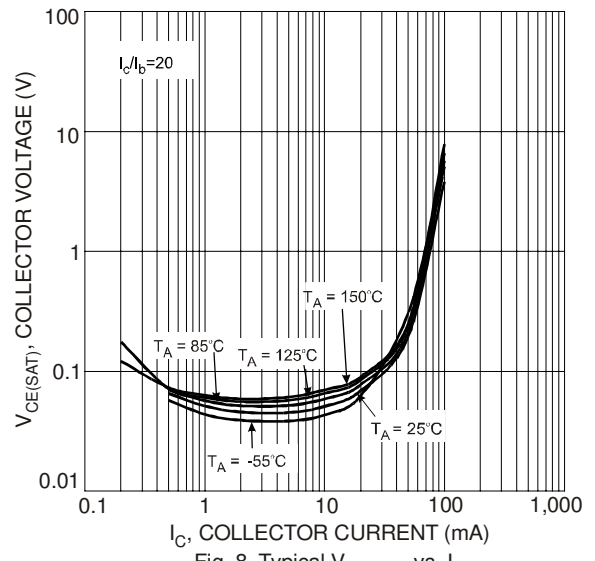


Fig. 8 Typical $V_{CE(SAT)}$ vs. I_C

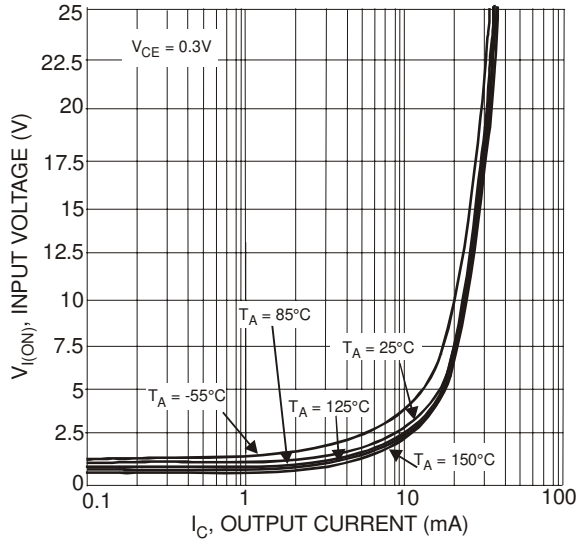


Fig. 9 Typical Input Voltage vs. Output Current

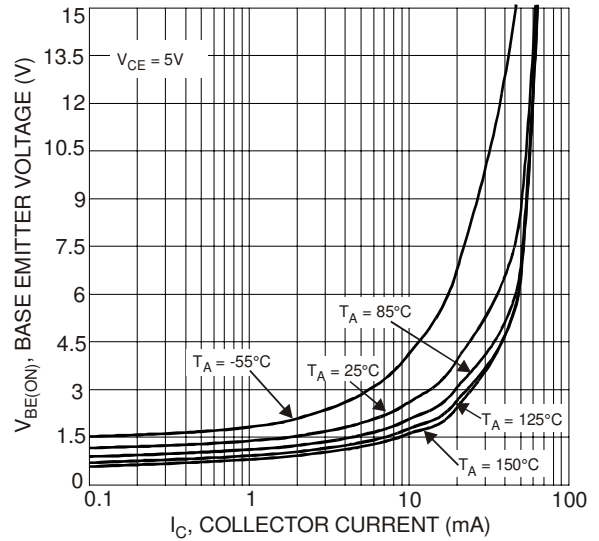


Fig. 10 Typical $V_{BE(ON)}$ vs. I_C

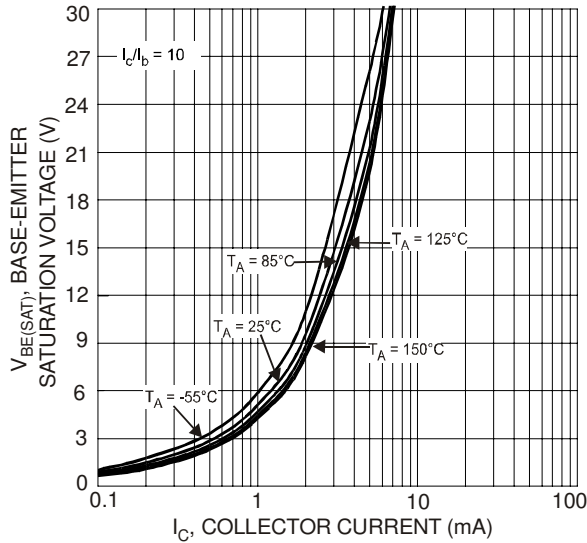


Fig. 11 Typical $V_{BE(SAT)}$ vs. I_C

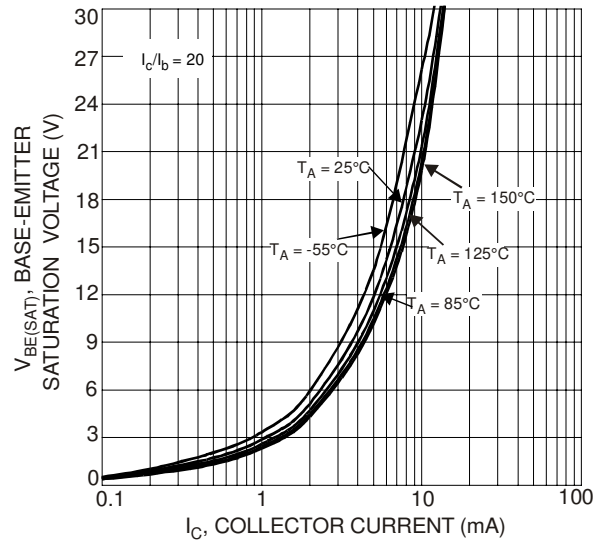


Fig. 12 Typical $V_{BE(SAT)}$ vs. I_C

Ordering Information (Note 4)

Device	Packaging	Shipping
DDC144NS-7	SOT-363	3000/Tape & Reel

Notes: 4. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information

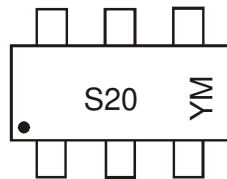


Fig. 13

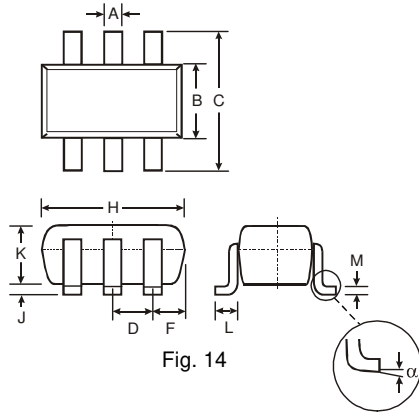
S20 = Product Type Marking Code,
 YM = Date Code Marking
 Y = Year, e.g., T = 2006
 M = Month, e.g., 9 = September

Date Code Key

Year	2005	2006	2007	2008	2009	2010	2011	2012
Code	S	T	U	V	W	X	Y	Z

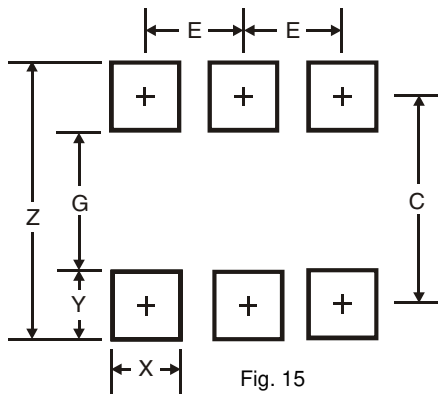
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Nominal	
F	0.30	0.40
H	1.80	2.20
J	—	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.25
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	SOT-363*
Z	2.5
G	1.3
X	0.42
Y	0.6
C	1.9
E	0.65

* Typical dimensions in mm

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